



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jean DE BERNARDI et al.

Group Art Unit: 3744

Application No.: 10/827,344

Examiner: M. ALI

Filed: April 20, 2004

Docket No.: 116037

For: ELECTRICAL AND ELECTRONIC COMPONENT CABINET FOR A
REFRIGERATION COMPRESSOR

REQUEST FOR RECONSIDERATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Office Action mailed May 24, 2005, reconsideration of the above-identified application is respectfully requested.

Claims 1-10 are pending.

The Office Action rejects claims 1, 2, 5-7 and 9 under 35 U.S.C. §102(b) over JP 2000-121210 to Matsushita, and claims 3, 4, 8 and 10 under 35 U.S.C. §103(a) over Matsushita in view of U.S. Patent 6,752,646 to McCoy. These rejections are respectfully traversed.

Matsushita discloses an electrical connection device of a hermetic compressor including a support 8 for electrical and electronic components 24, 4, 5 and a cap 10 having an open side face delimited by an edge whose shape at least partially matches the shape of a side wall of the compressor 1. The cap 10 is intended to be applied by its open side face against the side wall of the compressor.

However, in Matsushita, the side wall of the compressor does not form a wall of the cap when the cap is applied against a side wall of the compressor 1, as recited in independent claim 1.

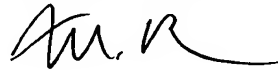
Instead, in Matsushita, the support 8 forms a wall of the cap when the cap is applied against a side wall of the compressor 1. The presence of the support 8 prevents the use of the side wall of the compressor to cool a connection device and the electrical and electronic components it contains. Consequently, it is not possible to use the heat exchange properties of the side wall of the refrigeration compressor to place the electrical and electronic components under favorable conditions of heat exchange. Therefore, heat dissipation of the electrical and electronic components placed inside the connection device brings about high temperatures inside the connection device. Because the components are not placed under favorable conditions of heat exchange, this prevents reducing the size and costs of the components. Thus, Matsushita does not address the problems solved by the invention, in particular to place the electrical components providing command, control and protection functions under favorable conditions of heat exchange.

McCoy does not make up for the deficiencies of Matsushita.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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WPB:MB/kzb

Date: July 26, 2005

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